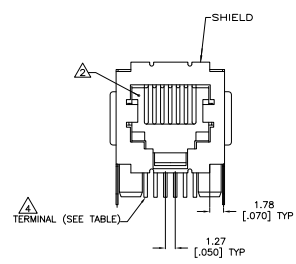
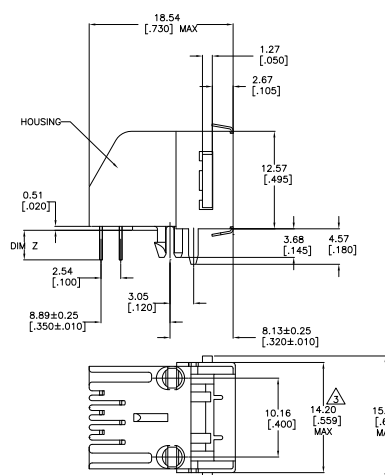
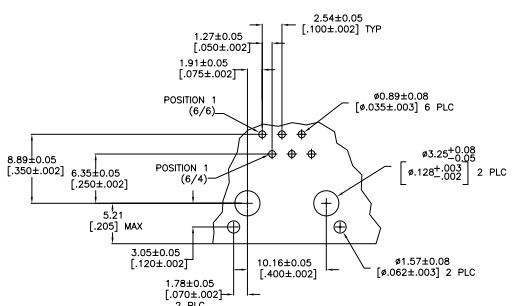
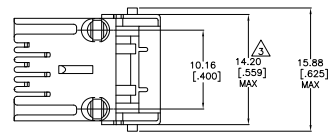


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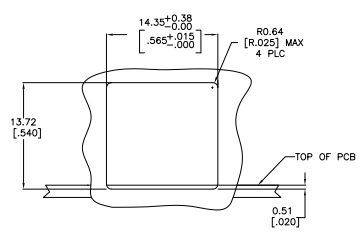
REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
E1		REVISED PER EDD-11-000033	23MAR11	RK	HMR



- 1 MATERIAL: HOUSING - PBT POLYESTER, COLOR: BLACK.
 TERMINAL - 0.36[.014] THICK PHOS-BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm[.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELD - 0.25[.010] THICK COPPER ALLOY PLATED WITH 3.0µm[.000120] MINIMUM REFLOWED TIN
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE
- △ TERMINALS FOR 5555140-2 LOCATED IN CENTER POSITIONS.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

TUBE	3.81±0.51 [150±.020]	6	5555140-6
TRAY	2.54±0.25 [100±.010]	6	5555140-4
	3.81±0.51 [150±.020]	4 △	5555140-2
	3.81±0.51 [150±.020]	6	5555140-1
PACKAGING	DIMENSION Z	TERMINALS REQUIRED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. **TE** Connectivity

DESIGNER	DATE	REVISED BY	REVISED DATE
108-1163	114-2048		

DESCRIPTION: MODULAR JACK ASSEMBLY, SHIELDED, 6 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS

SEE NOTE 1